

## Product Summary

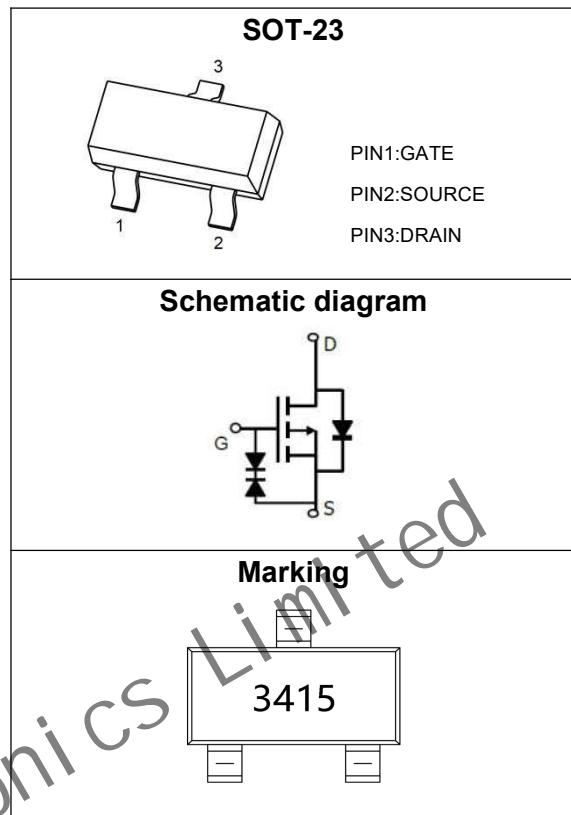
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-20V	26m $\Omega$ @-4.5V	-5.3A
	36m $\Omega$ @-2.5V	

## Features

- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired
- ESD Protected:2KV

## Applications

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



## Absolute Maximum rating ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

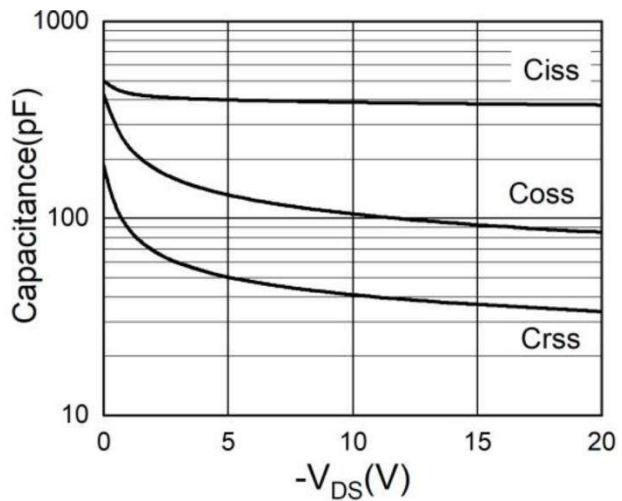
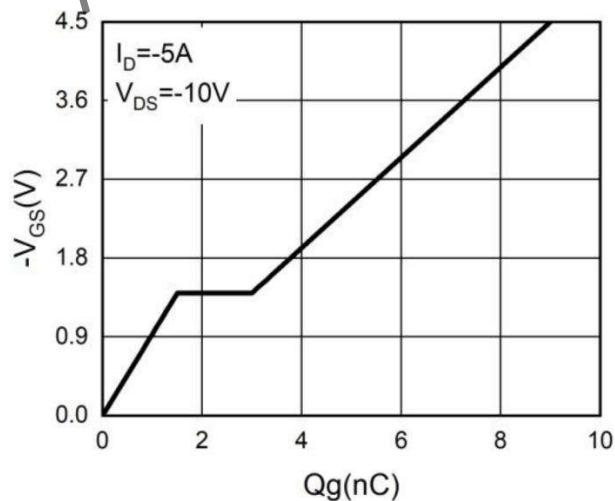
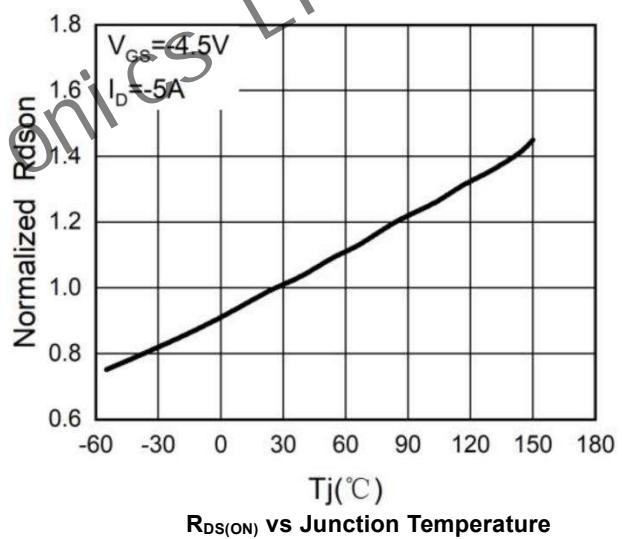
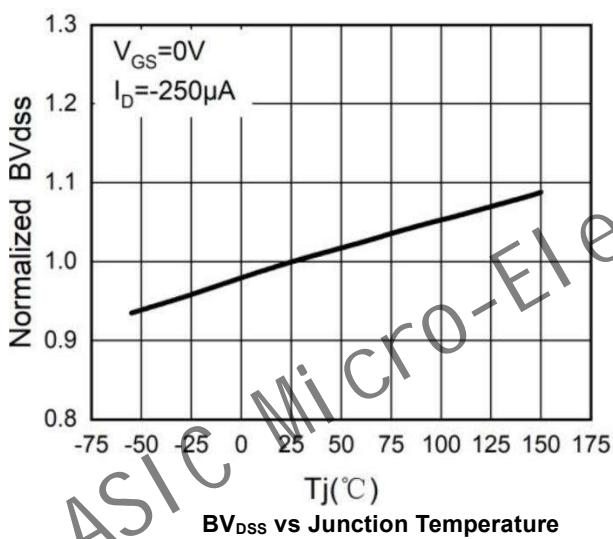
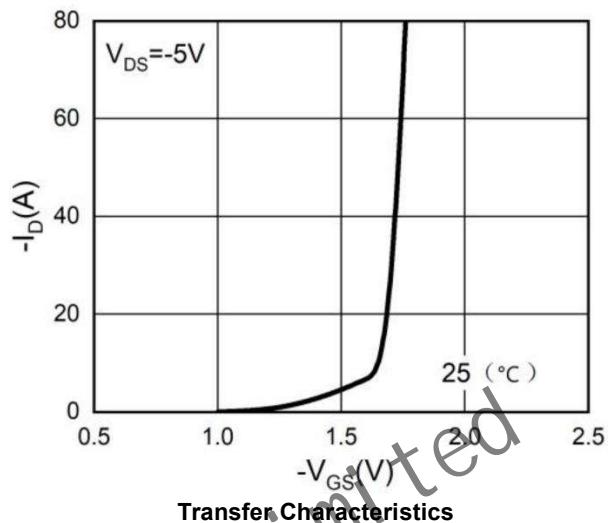
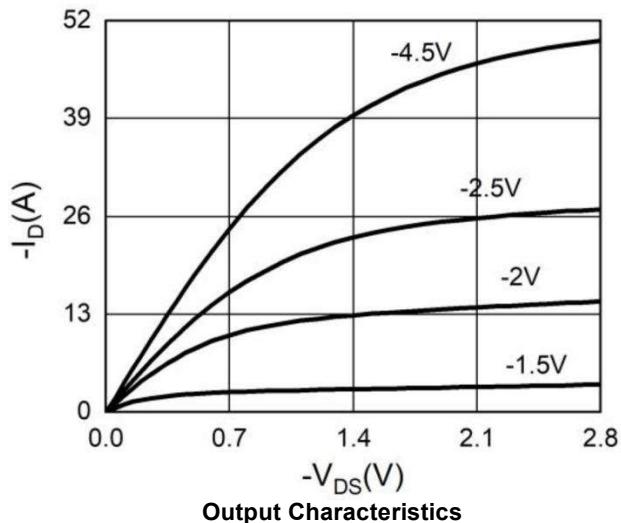
Parameter		Symbol	Value	Units
Drain-Source Voltage		$V_{DSS}$	-20	V
Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	-5.3	A
	$T_C = 70^\circ\text{C}$		-3.2	A
Drain Current - Pulsed <sup>1</sup>		$I_{DM}$	-16	A
Gate-Source Voltage		$V_{GSS}$	$\pm 12$	V
Power Dissipation	$T_C = 25^\circ\text{C}$	$P_D$	1.3	W
Thermal Resistance, Junction-to-Ambient		$R_{\theta JA}$	95	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

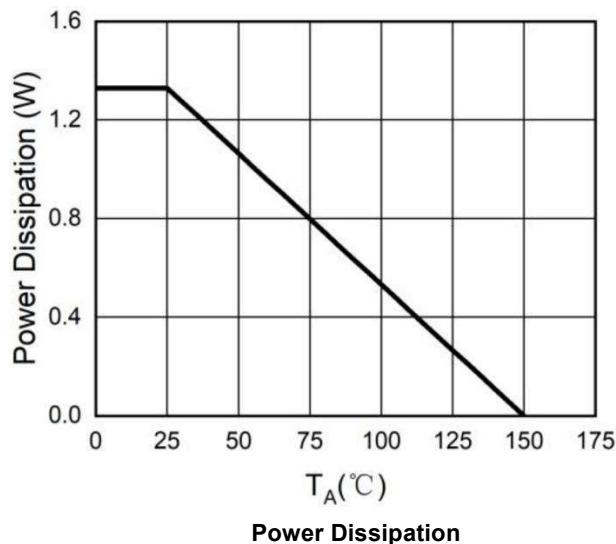
**Electrical Characteristics ( $T_A = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain - Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = -250\mu\text{A}$	-20			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate - Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 8\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 10$	$\mu\text{A}$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = -250\mu\text{A}$	-0.5		-1.0	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5\text{ V}, I_{\text{D}} = -2.5\text{ A}$		26	35	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{ V}, I_{\text{D}} = -2\text{ A}$		36	48	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, F = 1.0\text{Mhz}$		400		pF
Output Capacitance	$C_{\text{oss}}$			100		
Reverse Transfer Capacitance	$C_{\text{rss}}$			41		
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = -10\text{V}, I_{\text{D}} = -5\text{A}, V_{\text{GS}} = -4.5\text{V}$		9		nC
Gate-source Charge	$Q_{\text{gs}}$			1.6		
Gate-drain Charge	$Q_{\text{gd}}$			1.5		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -10\text{V}, V_{\text{GS}} = -4.5\text{V}, R_{\text{L}} = 2\Omega, R_{\text{GEN}} = 3\Omega$		12		ns
Turn-on Rise Time	$t_r$			35		
Turn-off Delay Time	$t_{\text{d}(\text{off})}$			30		
Turn-off Fall Time	$t_f$			10		
<b>Source - Drain Diode Characteristics</b>						
Drain to Source Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{SD}} = -5\text{A}, T_J = 25^\circ\text{C}$			-1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F = -5\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		170		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			60		nC

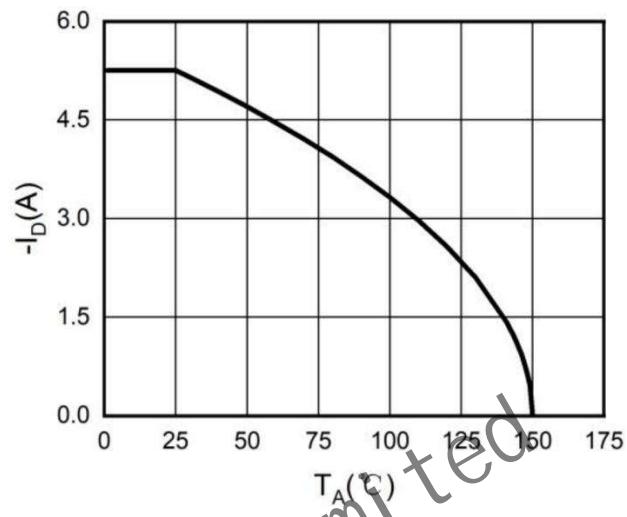
ASIC Micro-Electronics Limited

## Typical Characteristic

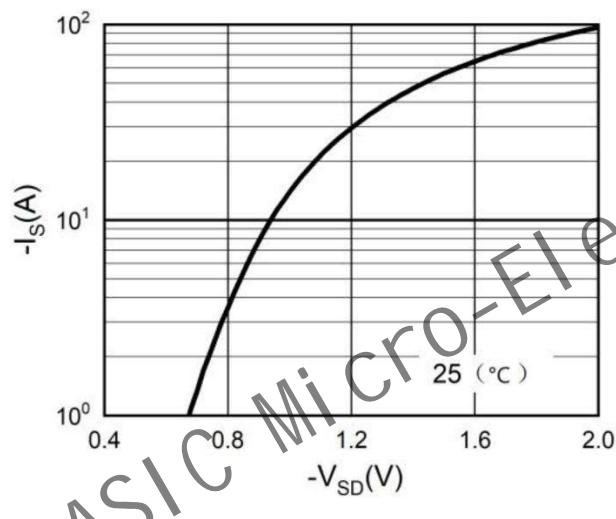




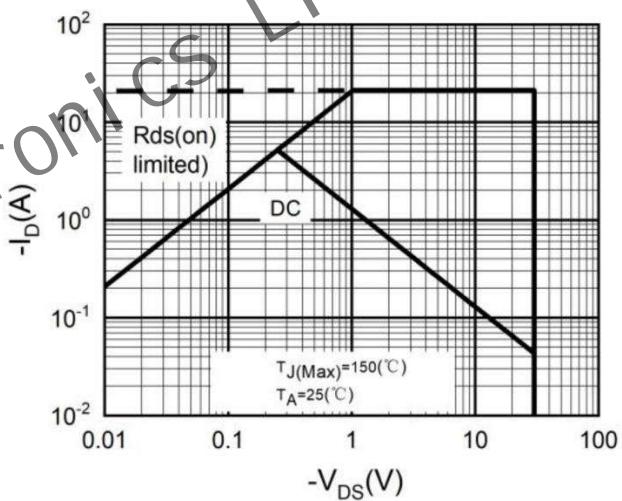
Power Dissipation



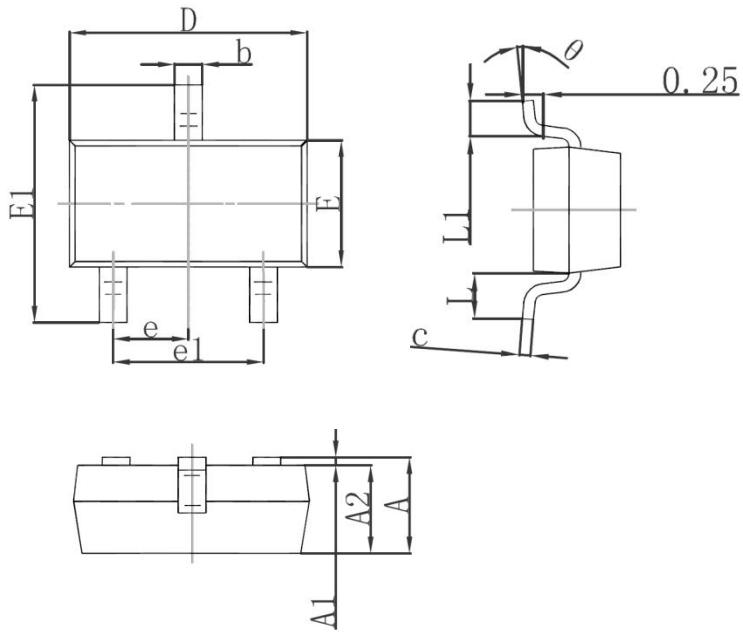
Drain Current



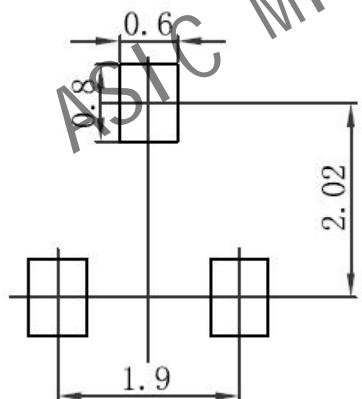
Body-Diode Characteristics



Maximum Safe Operating Area

**Dimension****SOT-23**

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

**Recommended Land Pattern****Note:**

1. Controlling dimension: in millimeters
2. General tolerance:  $\pm 0.05\text{mm}$
3. The pad layout is for reference only
4. Unit: mm